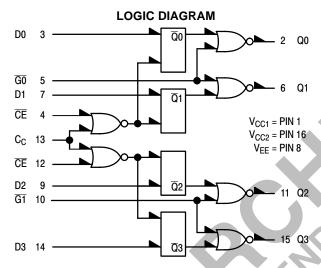
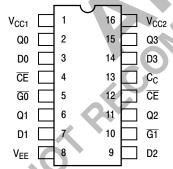
### **Quad Latch**

The MC10153 is a high speed, low power, MECL quad latch consisting of four bistable latch circuits with D type inputs and gated Q outputs. Open emitters allow a large number of outputs to be wire-ORed together. Latch outputs are gated, allowing direct wiring to a bus. When the clock is low, outputs will follow D inputs. Information is latched on positive going transition of the clock. The MC10153 provides the same logic function as the MC10133, except for inversion of the clock.

- $P_D = 310 \text{ mW typ/pkg (No Load)}$
- $t_{pd} = 4.0 \text{ ns typ}$
- $t_r$ ,  $t_f = 2.0$  ns typ (20%–80%)



#### **DIP PIN ASSIGNMENT**



Pin assignment is for Dual-in-Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

#### **TRUTH TABLE**

G	O	D	Q <sub>n+1</sub>
Н	Χ	Χ	L
L	X H	Χ	$Q_n$
L	L	L	L
L	L	Н	Н

 $C = C_C + \overline{CE}$ 



#### ON Semiconductor

http://onsemi.com

#### MARKING DIAGRAMS

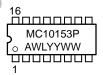


CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

#### **ORDERING INFORMATION**

Device	Package	Shipping		
MC10153L	CDIP-16	25 Units / Rail		
MC10153P	PDIP-16	25 Units / Rail		
MC10153FN	PLCC-20	46 Units / Rail		

#### **ELECTRICAL CHARACTERISTICS**

					7	Test Limits	<u> </u>			
		Pin Under	-30	0°C		+25°C		+85	5°C	
Characteristic	Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply Drain Current	Ι <sub>Ε</sub>	8		83			75		83	mAdc
Input Current	I <sub>inH</sub>	3 4 5 13		390 390 560 460			245 245 350 290		245 245 350 290	μAdc
	I <sub>inL</sub>	3	0.5		0.5			0.3		μAdc
Output Voltage Logic 1	V <sub>OH</sub>	2 2	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	Vdc
Output Voltage Logic 0	V <sub>OL</sub>	2 2 2	-1.890 -1.890 -1.890	-1.675 -1.675 -1.675	-1.850 -1.850 -1.850		-1.650 -1.650 -1.650	-1.825 -1.825 -1.825	-1.615 -1.615 -1.615	Vdc
Threshold Voltage Logic 1	V <sub>ОНА</sub>	2 2 2† 2‡ 2; 2; 2	-1.080 -1.080 -1.080 -1.080 -1.080 -1.080 -1.080		-0.980 -0.980 -0.980 -0.980 -0.980 -0.980 -0.980			-0.910 -0.910 -0.910 -0.910 -0.910 -0.910 -0.910 -0.910	S	Vdc
Threshold Voltage Logic 0	Vola	2 2 2 2† 2‡ 2‡		-1.655 -1.655 -1.655 -1.655 -1.655 -1.655		OP	-1.630 -1.630 -1.630 -1.630 -1.630 -1.630		-1.595 -1.595 -1.595 -1.595 -1.595 -1.595	Vdc
Switching Times (50Ω Load)										ns
Propagation Delay	$t_{3+2+}$ $t_{4-2+}$ $t_{5-2+}$ $t_{setup}$ $t_{hold}$	2 2 2 2 3 3	1.0 1.0 1.0 2.5 1.5	5.6 5.6 3.2	1.0 1.0 1.0 2.5 1.5	4.0 4.0 2.0 0.7 0.7	5.4 5.6 3.1	1.1 1.2 1.0 2.5 1.5	5.9 6.2 3.4	
Rise Time (20 to 80%)	t <sub>2+</sub>	2	1.0	3.6	1.1	2.0	3.5	1.1	3.8	
Fall Time (20 to 80%)	t <sub>2-</sub>	2	1.0	3.6	1.1	2.0	3.5	1.1	3.8	

Output level to be measured after a clock pulse has been applied to the clock input (Pin 4)	$\neg$ $\lor$ <sub>IHm</sub>	ıa
	 <u></u> —— <sub>VILm</sub>	in

<sup>‡</sup> Data input at proper high/low level while clock pulse is high so that device latches ar proper high/low level for test. Levels are measured after device has latched.

<sup>\*</sup> Latch set to zero state before test.

#### **ELECTRICAL CHARACTERISTICS** (continued)

			TEST VOLTAGE VALUES (Volts)						
@ Test Temperature			V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>EE</sub>		
			-30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
	+25°C			-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
			Pin	TEST V	OLTAGE A	PPLIED TO	PINS LISTED I	BELOW	(v, )
Characteris	tic	Symbol	Under Test	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>EE</sub>	(V <sub>CC</sub> ) Gnd
Power Supply Drain Cu	urrent	Ι <sub>Ε</sub>	8		13			8	1, 16
Input Current		l <sub>inH</sub>	3 4 5 13	3 4 5 13				8 8 8	1, 16 1, 16 1, 16 1, 16
		l <sub>inL</sub>	3		3			8	1, 16
Output Voltage	Logic 1	V <sub>OH</sub>	2 2	3 3	4 13			8 8	1, 16 1, 16
Output Voltage	Logic 0	V <sub>OL</sub>	2 2 2	3,5	3,13 13 3,4			8 8 8	1, 16 1, 16 1, 16
Threshold Voltage	Logic 1	V <sub>OHA</sub>	2 2 2 2† 2‡ 2; 2 2	3 3 3 3	4 4 4	3	4 13	8 8 8 8 8 8	1, 16 1, 16 1, 16 1, 16 1, 16 1, 16 1, 16 1, 16
Threshold Voltage	Logic 0	V <sub>OLA</sub>	2 2 2 2† 2† 2‡ 2;	3 3 3	4 4 4	5	3	8 8 8 8 8	1, 16 1, 16 1, 16 1, 16 1, 16 1, 16
Switching Times	(50Ω Load)			+1.11 V		Pulse In	Pulse Out	-3.2 V	+2.0 V
Propagation Delay		t <sub>3+2+</sub> t <sub>4-2+</sub> t <sub>5-2+</sub> t <sub>setup</sub> t <sub>hold</sub>	2 2 2 3 3	3*		3 4 5 3 3	2 2 2 2 2	8 8 8 8	1, 16 1, 16 1, 16 1, 16 1, 16
Rise Time	(20 to 80%)	t <sub>2+</sub>	2			3	2	8	1, 16
Fall Time	(20 to 80%)	t <sub>2-</sub>	2			3	2	8	1, 16

<sup>†</sup> Output level to be measured after a clock pulse has been applied to the clock input (Pin 4) VILmin VILmin

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

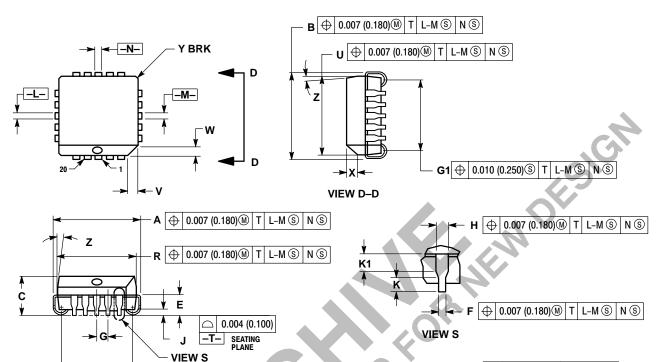
<sup>‡</sup> Data input at proper high/low level while clock pulse is high so that device latches ar proper high/low level for test. Levels are measured after device has latched.

<sup>\*</sup> Latch set to zero state before test.

#### PACKAGE DIMENSIONS

#### PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



#### NOTES:

- OTES:

  1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

  2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

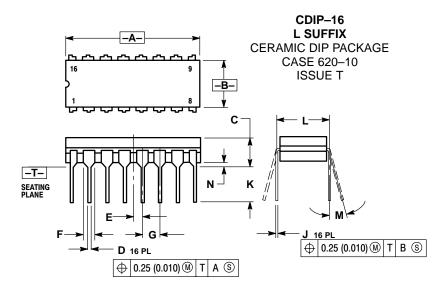
  4. DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300).
- DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OENICE NOT RECO

#### PACKAGE DIMENSIONS



#### NOTES:

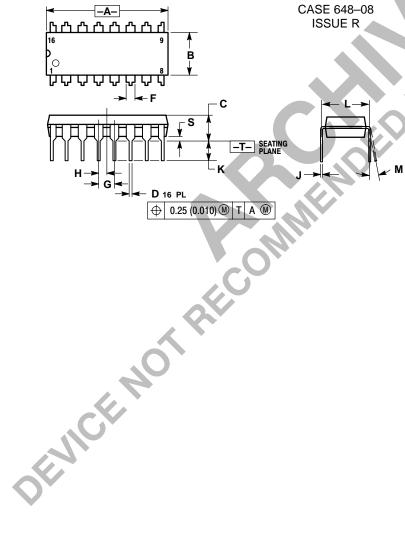
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
   DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

  DIMENSION F MAY NARROW TO 0.76 (0.030)
  WHERE THE LEAD ENTERS THE CERAMIC
  BODY.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Е	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300 BSC		7.62 BSC		
М	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

#### PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

# **Notes**



# **Notes**





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